iM5223



N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☑ Surface-mounted package
- ☑ Low gate charge

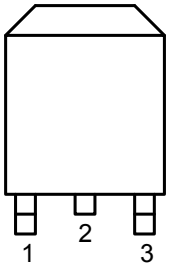
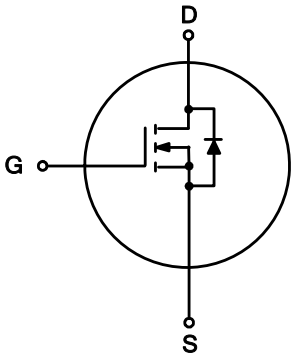
1.2 Applications

- ☑ Motor driver appliances
- ☑ Adapter appliances
- ☑ High power inverter system

1.3 Quick reference

- ☑ BV ≧ 100 V
- ☑ P_{tot} ≦ 35 W
- ☑ I_D ≦ 11 A
- ☑ $R_{DS(ON)}$ ≦ 140 mΩ @ V_{GS} = 10 V
- ☑ $R_{DS(ON)}$ ≦ 150 mΩ @ V_{GS} = 4.5 V

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)		
2	Drain(D)		
3	Source(S)		

Top View

TO252



3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	T_C = 25 ℃	100	-	V
V_{GS}	Gate-Source Voltage	T_C = 25 ℃	-	± 20	V
I_D*	Drain Current	T_C = 25 ℃, V_{GS} = 10 V	-	11	A
		T_C = 100 ℃, V_{GS} = 10 V	-	6.9	A
I_{DM}*,**,***	Pulsed Drain Current	T_C = 25 ℃, V_{GS} = 10 V	-	40	A
P_{tot}*	Total Power Dissipation	T_C = 25 ℃	-	35	W
T_{stg}	Storage Temperature		- 55	150	℃
T_J	Junction Temperature		-	150	℃
$R_{\theta JC}$*	Thermal Resistance- Junction to Case		-	3.5	℃ / W
$R_{\theta JA}$*	Thermal Resistance- Junction to Ambient		-	62.5	℃ / W

Notes：

* Surface Mounted on 1 in^2 pad area, t ≤ 10 sec

** Pulse width ≤ 300 μs, duty cycle ≤ 2 %

*** limited by bonding wire

4. Marking Information

Product Name	Marking
iM5223	iM5223 XXXXX X : Date Code

5. Ordering Code

iM5223 □ → Assembly Material	Assembly Material G: Halogen and Lead Free Device

Note: inergy defines " Green " as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC / JEDEC J-STD-020C)



6. Electrical Characteristics (T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_{DS} = 250 µA	100	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_{DS} = 250 µA	1	1.8	3	V
I_{DSS}	Drain Leakage Current	V_{DS} = 100 V, V_{GS} = 0 V	-	-	1	µA
I_{GSS}	Gate Leakage Current	V_{GS} = ± 20 V, V_{DS} = 0 V	-	-	± 100	nA
$R_{DS(ON)}$[a]	Channel On-State Resistance	V_{GS} = 10 V, I_D = 5 A	-	115	140	mΩ
		V_{GS} = 4.5 V, I_D = 3 A	-	120	150	
Diode Characteristics						
V_{SD}[a]	Diode Forward Voltage	I_{SD} = 5 A, V_{GS} = 0 V	-	-	1.3	V
t_{rr}	Reverse Recovery Time	I_{SD} = 5 A, dI_{SD} / dt = 100 A / µs	-	20	-	nS
Q_{rr}	Reverse Recovery Charge		-	19	-	nC
Dynamic Characteristics[b]						
C_{iss}	Input Capacitance	V_{GS} = 0 V, V_{DS} = 50 V Frequency = 1 MHz	-	1095	-	pF
C_{oss}	Output Capacitance		-	26	-	
C_{rss}	Reverse Transfer Capacitance		-	25	-	
t_d(on)	Turn-on Delay Time	V_{DS} = 50 V, V_{GEN} = 10 V, R_G = 4.5 Ω, R_L = 10 Ω, I_{DS} = 5 A	-	6.8	-	nS
t_r	Turn-on Rise Time		-	2.6	-	
t_d(off)	Turn-off Delay Time		-	19	-	
t_f	Turn-off Fall Time		-	7.4	-	
Gate Charge Characteristics[b]						
Q_g	Total Gate Charge	V_{GS} = 10 V, V_{DS} = 50 V, I_{DS} = 5 A	-	19	-	nC
Q_{gs}	Gate-Source Charge		-	4.3	-	
Q_{gd}	Gate-Drain Charge		-	2.1	-	

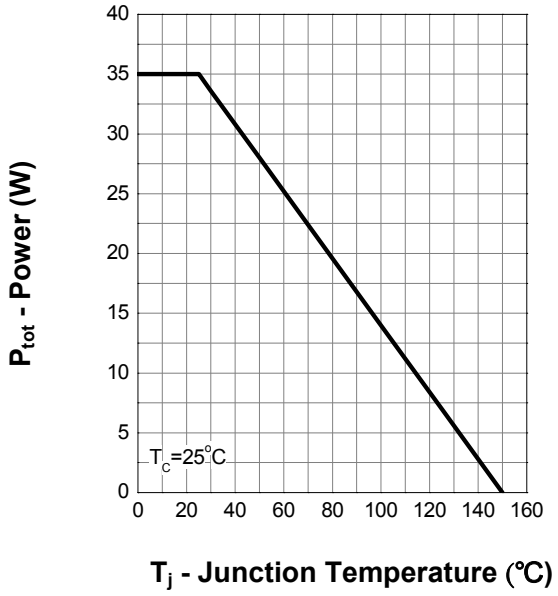
Notes :

a : Pulse test ; pulse width ≤ 300 µs, duty cycle ≤ 2 %

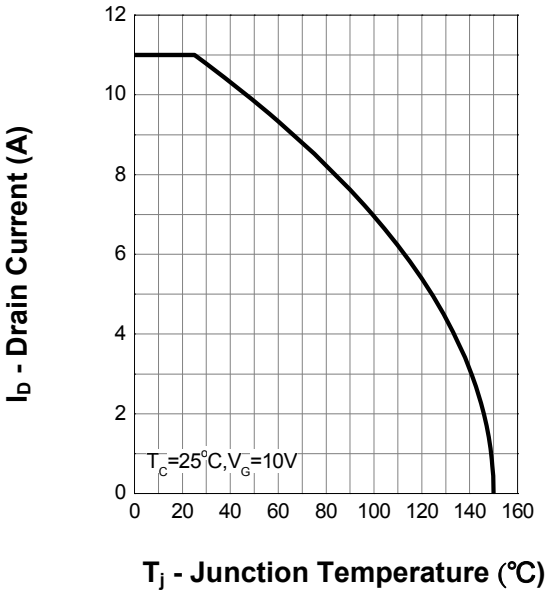
b : Guaranteed by design, not subject to production testing

7. Typical Characteristics

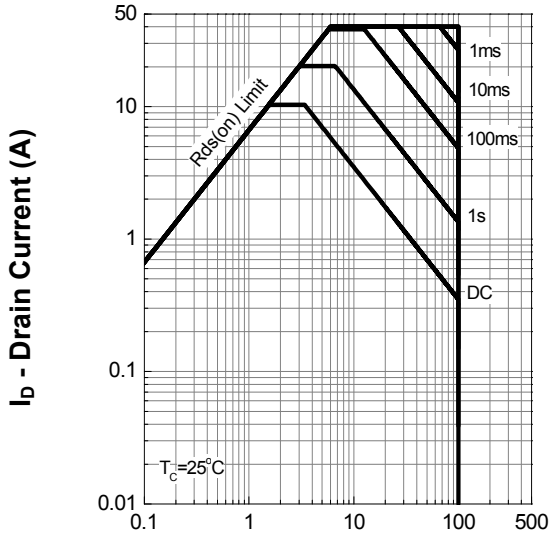
Power Dissipation



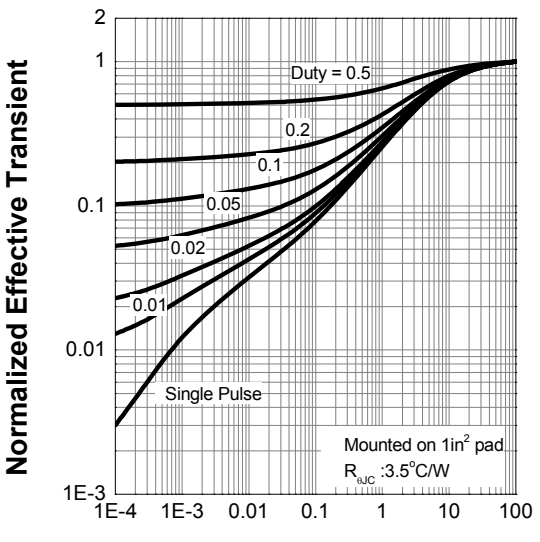
Drain Current



Safe Operation Area

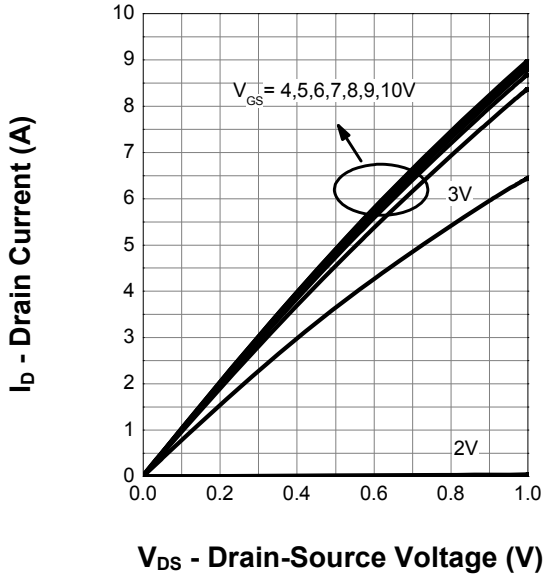


Thermal Transient Impedance

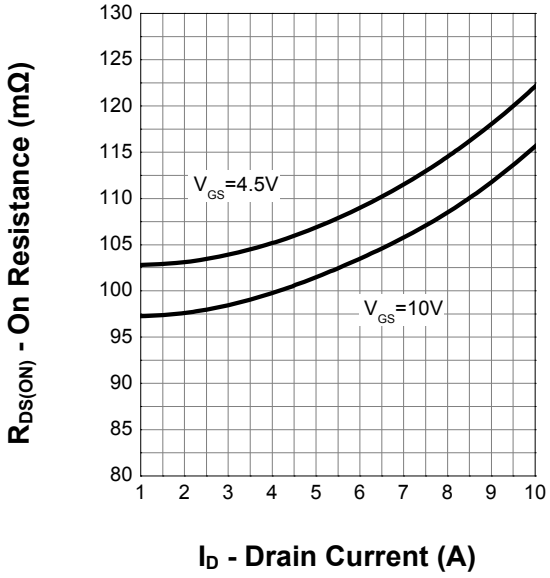


7. Typical Characteristics (cont.)

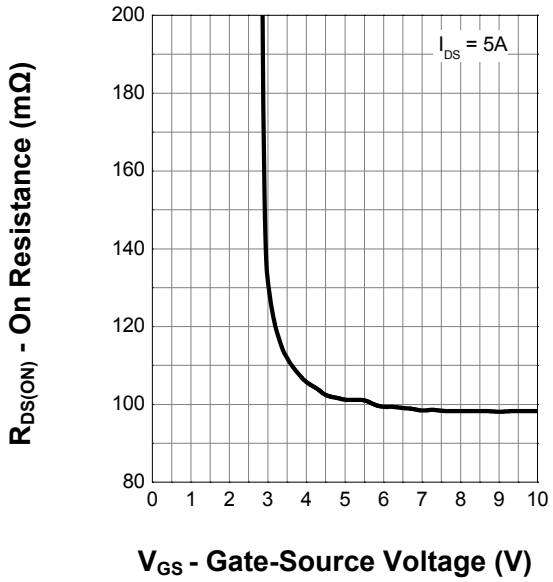
Output Characteristics



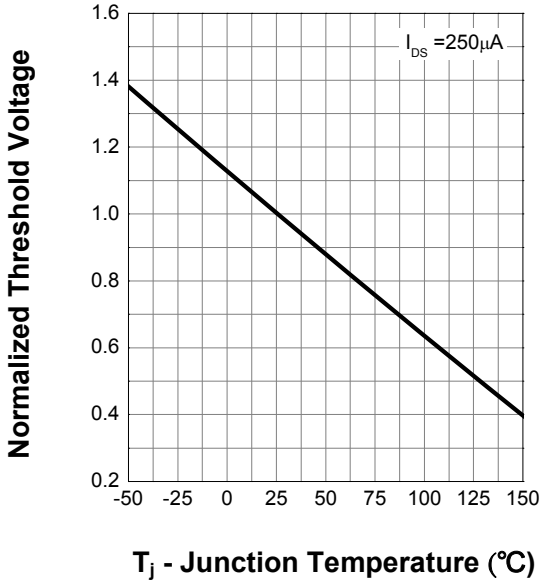
Drain-Source On Resistance



Transfer Characteristics

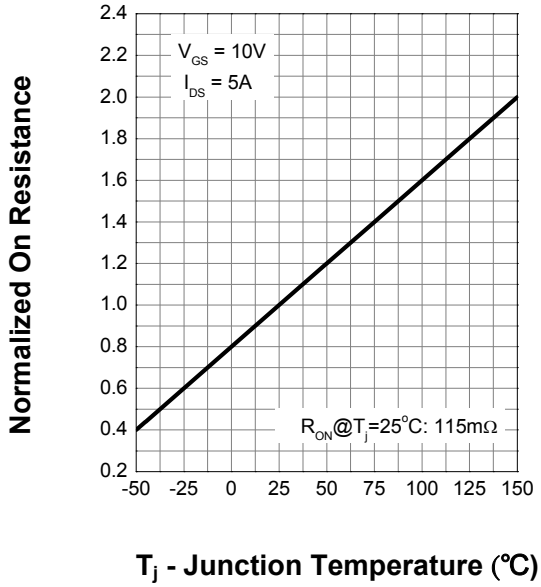


Gate Threshold Voltage

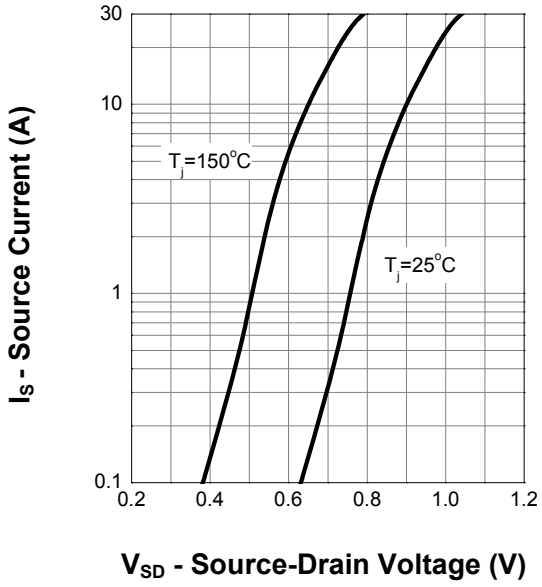


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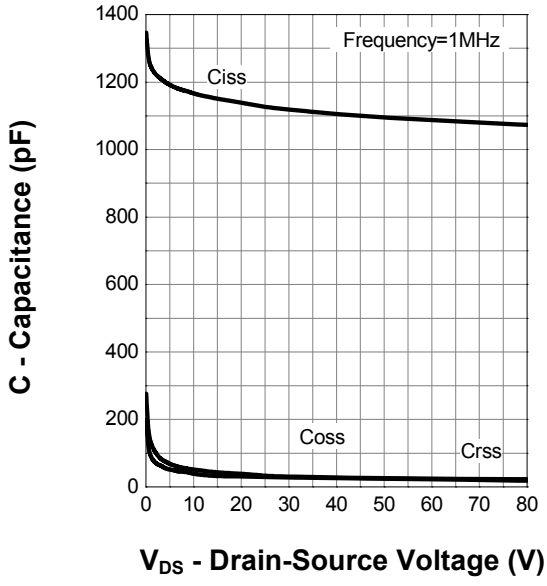
Drain-Source On Resistance



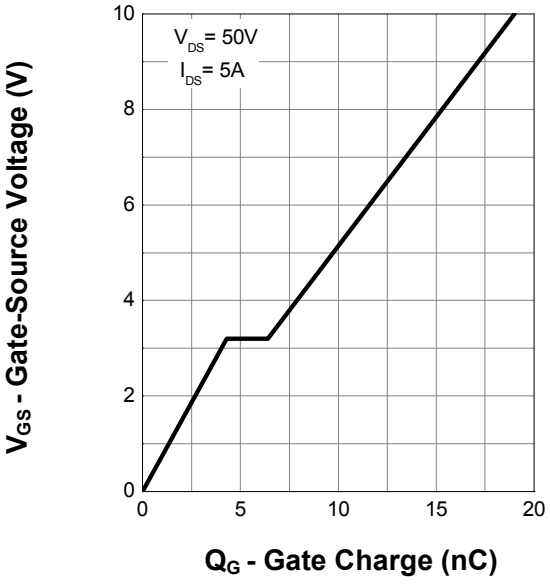
Source-Drain Diode Forward



Capacitance

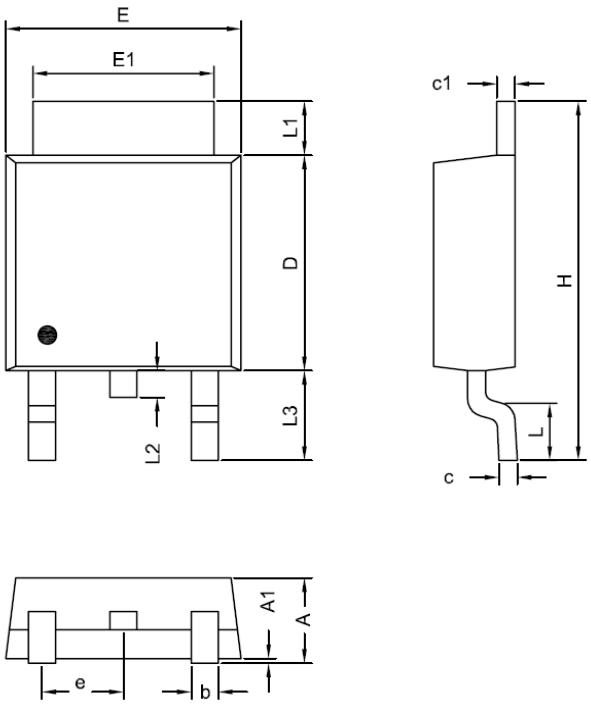


Gate Charge



8.Package Dimensions

TO252-3L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.19	2.38
A1	0.02	0.13
D	5.30	6.40
E	6.35	6.80
E1	5.20	5.50
c	0.40	0.60
c1	0.40	0.60
b	0.55	0.85
e	2.30 BCS	
L	1.00	1.80
L1	0.70	1.80
L2	0.70 BCS	
L3	2.40	2.80
H	9.20	10.40